Final Product Change Notification

201203005F01

Issue Date: 13-Jul-2013
Effective Date: 11-Oct-2013

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QUALITY

Management Summary

Final announcement of products processed in PM58 transferred within NXP Nijmegen from ICN6 to ICN8 due to factory closure

Change Category

Wafer Fab process	Assembly Process	Product Marking	Design
Wafer Fab materials	Assembly Materials	Electrical spec./Test coverage	Mechanical Specification
Wafer Fab location	Assembly Location	Test Location	Packing/Shipping/Labeling

Transfer PM58 process from ICN6 to ICN8 within NXP Nijmegen (The Netherlands)

Details of this Change

Transfer within NXP Nijmegen (The Netherlands) from ICN6 (PM58 process) to ICN8 (PC50SSM process)

- Process and products will be transferred in 2013, production ramp down and closure of ICN6 planned 1 January 2014

- No change in die layout, all masks are produced from the same GDS2 file
- No change in ordering code 12NC's and product type number

Why do we Implement this Change

- Move production to 8" wafers

- Capacity increase to address customer demand

Identification of Affected Products

Applied wafer fab is indicated on the third line of the product marking (top side) first character, if space permits:

"U"= NXP ICN6
"T"= NXP ICN8

Product Availability

Sample Information

Samples are available upon request
Requested customer engineering' samples based on the APCN 201203005A will be available type by type.

Production

Planned first shipment 05-Oct-2013

Impact

- No impact
- No change in data sheet, form, fit, function, quality or reliability anticipated

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201203005A	27-Jun-2012		Transfer PM58 process from ICN6 to ICN8 within NXP Nijmegen (The Netherlands)

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 12-Aug-2013.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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